

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TSUBASA WATANABE	11/06/2017
TSUTOMU KONO	11/08/2017
TAKAYUKI YOGO	11/07/2017
HIROAKI HOSHIKA	11/07/2017
RECEIVING PARTY DATA	
Name:	HITACHI AUTOMOTIVE SYSTEMS, LTD.
Street Address:	2520, TAKABA
City:	HITACHINAKA-SHI, IBARAKI
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15576356
CORRESPONDENCE DATA	
Fax Number:	(202)628-8844
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-624-2500
Email:	eoconnell@crowell.com
Correspondent Name:	CROWELL & MORING LLP INTELLECTUAL PROPER
Address Line 1:	P.O. BOX 14300
Address Line 4:	WASHINGTON, D.C. 20044-4300
ATTORNEY DOCKET NUMBER:	114617.PA601US
NAME OF SUBMITTER:	MICHAEL H. JACOBS
SIGNATURE:	/Michael H. Jacobs/
DATE SIGNED:	11/22/2017
Total Attachments: 2	
source=PA601US_Assignment#page1.tif	
source=PA601US_Assignment#page2.tif	

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by HITACHI AUTOMOTIVE SYSTEMS, LTD., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki, JAPAN receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

RESIN MOLDING AND SENSOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI AUTOMOTIVE SYSTEMS, LTD.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

DATE SIGNED
(署名日)

1) <u>Tsubasa Watanabe</u>	<u>Tsubasa WATANABE</u>	<u>11/6/2019</u>
2) _____	<u>Tsutomu KONO</u>	_____
3) _____	<u>Takayuki YOGO</u>	_____
4) _____	<u>Hiroaki HOSHIKA</u>	_____
5) _____	_____	_____
6) _____	_____	_____
7) _____	_____	_____
8) _____	_____	_____

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI AUTOMOTIVE SYSTEMS, LTD.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	DATE SIGNED (署名日)
1) _____ Tsubasa WATANABE	_____
2) <u>Tsutomu Kono</u> Tsutomu KONO	<u>11/8/2017</u>
3) <u>Takayuki Yogo</u> Takayuki YOGO	<u>11/7/2017</u>
4) <u>Hiroaki Hoshika</u> Hiroaki HOSHIKA	<u>11/7/2017</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____